

MOUNTING STRUCTURE FOR CHIP COMPONENT

ABSTRACT

5 A mounting structure for a chip component according to the present disclosure
comprises chip component 2 including both terminal electrodes, and two lands 3 on a
printed wiring board 1, both terminal electrodes being soldered to two lands 3 by a flow
soldering method.. The size of small SMD component 2 is 0.6 mm × 0.3 mm, and the
dimension between two lands 3 is more than or equal to 0.23 mm and less than or equal to
10 0.25 mm.

FIG. 1